



XA-9890
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Takashi MIWA et al.

Appln. No.: 10/606,891

Group Art Unit: 2824

Filed: June 27, 2003

Examiner: A. Tran

For: STACKED LARGE-SCALE INTEGRATED CIRCUIT (LSI)
SEMICONDUCTOR DEVICE WITH MINIATURIZATION AND THINNING OF
PACKAGE (AS AMENDED)

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AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
Sir:

In response to the non-final Office Action mailed on
January 11, 2005, please amend the above-identified patent
application as indicated below.

Amendments to the specification begin on page 2 of this
paper.

Amendments to the claims are reflected in the listing
of claims, which begins on page 3 of this paper.

Amendments to the drawings begin on page 11 of this
paper and include two replacement sheets.

Remarks begin on page 12 of this paper.